

## Modules vs. Down Board DRAM

Highly Ruggedized for Mission-Critical Environments

# Reasons for transitioning to SMART Modules now

- Scalability (density and speed)
- Board space
- Thermal management
- Ease of routing
- Signal integrity
- Design flexibility
- Ruggedization
- Reliability
- Environmental protection
- Qualification

## Successful Use Case Examples



SO-DIMMs

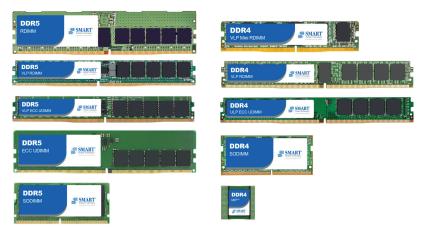




Mini-DIMMs

DIMMs and VLP DIMMs

## **DDR5 and DDR4 Modules**



For more information, please visit: www.smartm.com

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\*Product images are for promotional purposes only. Labels may not be representative of the actual product.

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